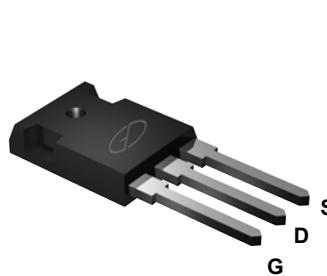
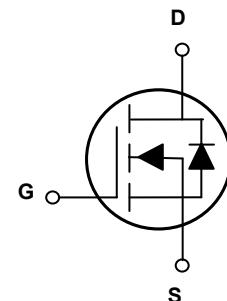


## Main Product Characteristics

$V_{DS}$	100V
$R_{DS(ON)}$	2.7mΩ (Max)
$I_D$	200A



TO-247



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSFA10200 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous ( $T_C=25^\circ\text{C}$ ) <sup>1</sup>	$I_D$	200	A
Drain Current-Continuous ( $T_C=100^\circ\text{C}$ )		142	
Drain Current-Pulsed <sup>2</sup>	$I_{DM}$	800	A
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	961	mJ
Power Dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	400	W
Power Dissipation-Derate above 25°C		3.2	W/°C
Thermal Resistance, Junction-to-Ambient <sup>4</sup>	$R_{\theta JA}$	50	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.32	°C/W
Operating Junction Temperature Range	$T_J$	-55 To +150	°C
Storage Temperature Range	$T_{STG}$	-55 To +150	°C

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	100	-	-	V
Drain-Source Leakage Current	$\text{I}_{\text{DSS}}$	$\text{V}_{\text{DS}}=100\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{T}_J=25^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$\text{V}_{\text{DS}}=100\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{T}_J=125^\circ\text{C}$	-	-	20	$\mu\text{A}$
Gate-Source Leakage Current	$\text{I}_{\text{GSS}}$	$\text{V}_{\text{GS}}=\pm 20\text{V}$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance	$\text{R}_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=60\text{A}$	-	2.1	2.7	$\text{m}\Omega$
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}, \text{I}_D=250\mu\text{A}$	2.1	3	3.9	V
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge	$\text{Q}_g$	$\text{V}_{\text{DS}}=50\text{V}, \text{I}_D=90\text{A}, \text{V}_{\text{GS}}=10\text{V}$	-	165	-	nC
Gate-Source Charge	$\text{Q}_{\text{gs}}$		-	61	-	
Gate-Drain Charge	$\text{Q}_{\text{gd}}$		-	40	-	
Turn-On Delay Time	$\text{t}_{\text{d}(\text{on})}$	$\text{V}_{\text{DS}}=50\text{V}, \text{R}_G=3\Omega, \text{V}_{\text{GS}}=10\text{V}, \text{I}_D=90\text{A}$	-	33	-	nS
Rise Time	$\text{t}_r$		-	46	-	
Turn-Off Delay Time	$\text{t}_{\text{d}(\text{off})}$		-	119	-	
Fall Time	$\text{t}_f$		-	44	-	
Input Capacitance	$\text{C}_{\text{iss}}$	$\text{V}_{\text{DS}}=50\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{F}=1\text{MHz}$	-	10430	-	pF
Output Capacitance	$\text{C}_{\text{oss}}$		-	1263	-	
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$		-	35	-	
Gate Resistance	$\text{R}_g$	$\text{F}=1\text{MHz}$	-	2.2	-	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$\text{I}_s$	MOSFET symbol showing the integral reverse p-n junction diode.	-	-	200	A
Pulsed Source Current	$\text{I}_{\text{SM}}$		-	-	800	A
Diode Forward Voltage	$\text{V}_{\text{SD}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_s=60\text{A}$	-	1	1.2	V
Reverse Recovery Time	$\text{t}_{\text{rr}}$	$\text{I}_F=90\text{A}, \text{di}/\text{dt}=100\text{A}/\mu\text{s}, \text{T}_J=25^\circ\text{C}$	-	85	-	nS
Reverse Recovery Charge	$\text{Q}_{\text{rr}}$		-	0.26	-	$\mu\text{C}$

Note:

1. Pulse test: pulse width  $\leqslant 300\text{us}$ , duty cycle  $\leqslant 2\%$ .
2. Repetitive rating: Pulsed width limited by maximum junction temperature.
3.  $L=0.5\text{mH}, V_{\text{DD}}=80\text{V}, I_{\text{AS}}=62\text{A}$ , starting  $T_J=25^\circ\text{C}$ .
4. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

## Typical Electrical and Thermal Characteristic Curves

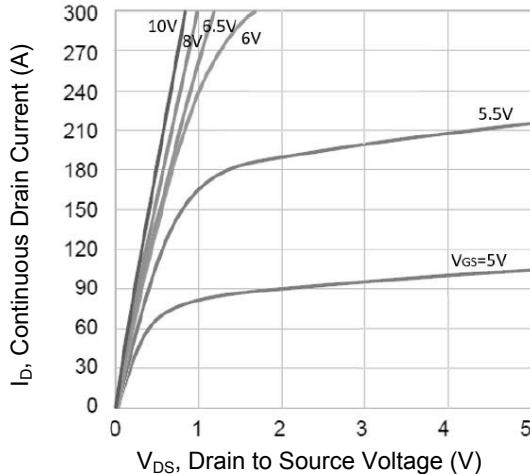


Figure 1. Output Characteristics

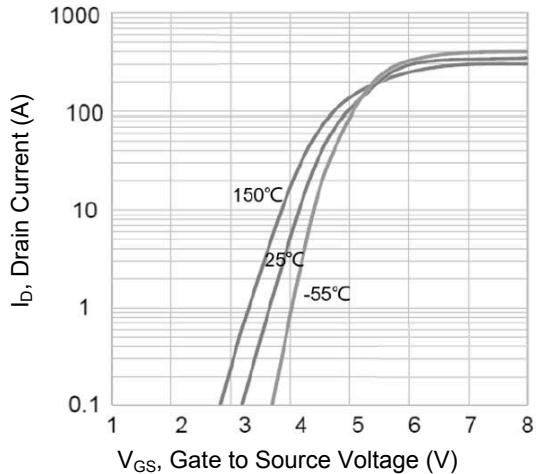


Figure 2. Transfer Characteristics

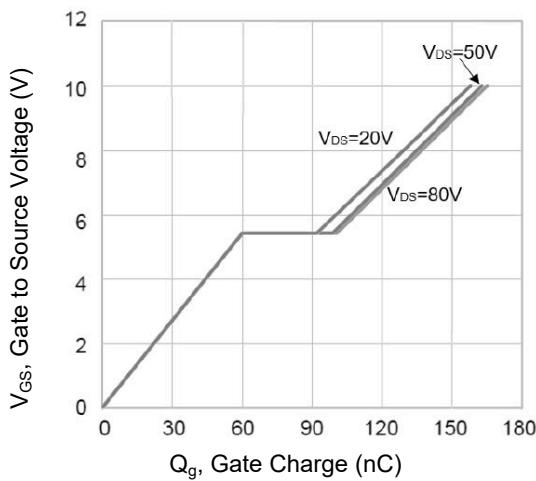


Figure 3. Gate Charge Waveform

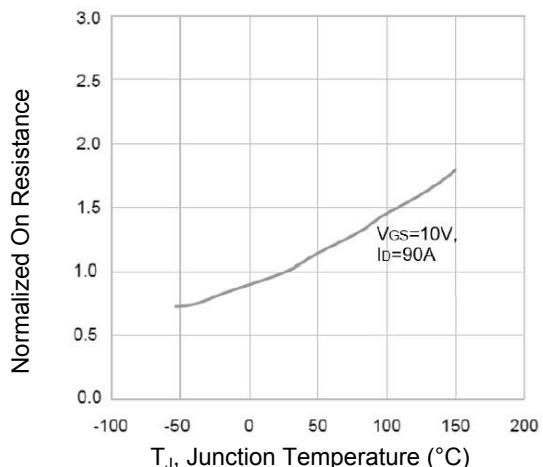


Figure 4. Normalized  $R_{DS(ON)}$  vs. Junction Temperature

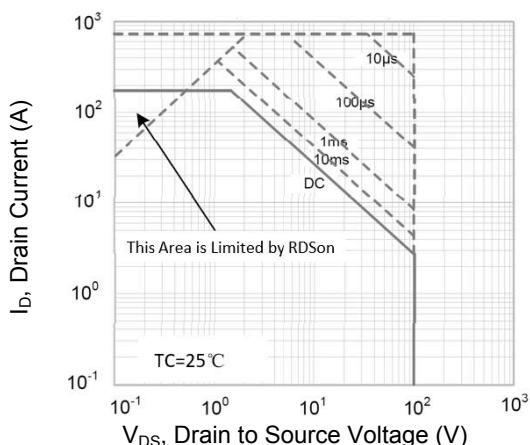


Figure 5. Safe Operation Area

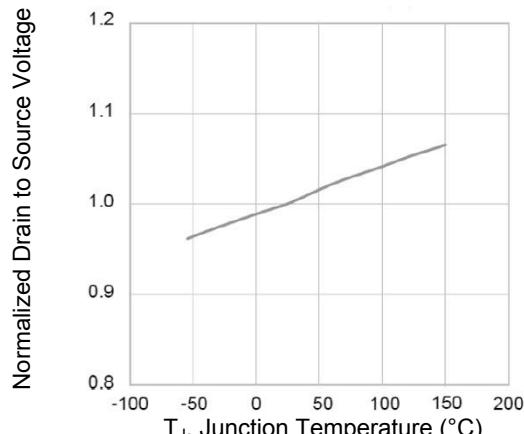


Figure 6. Normalized  $BV_{DSS}$  vs. Junction Temperature

### Typical Electrical and Thermal Characteristic Curves

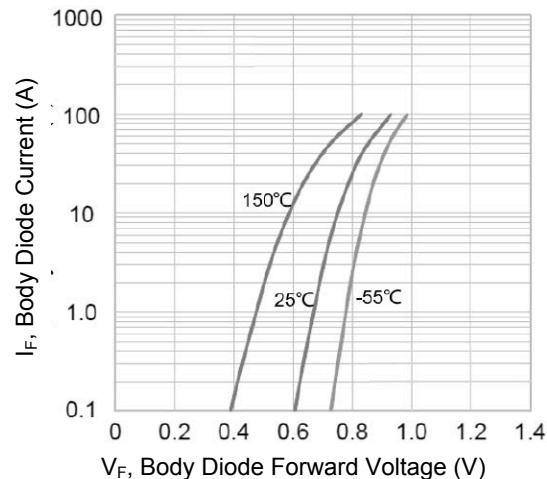


Figure 7. Body Diode Characteristics

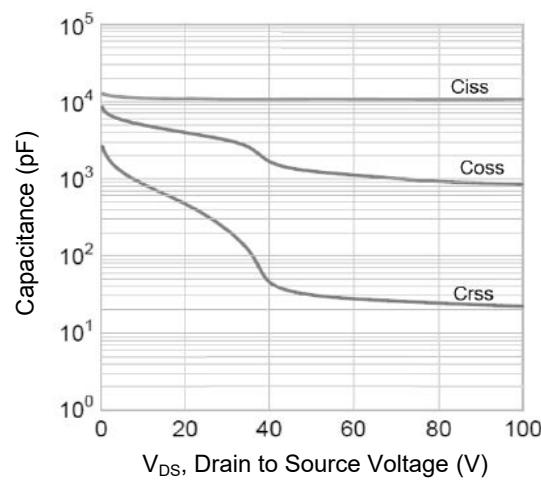
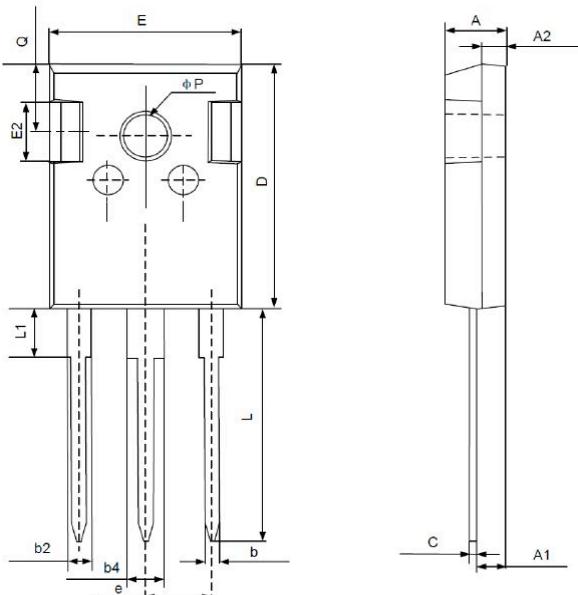


Figure 8. Capacitance Characteristics

### Package Outline Dimensions (TO-247)



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	4.800	5.200	0.189	0.205
A1	2.210	2.590	0.087	0.102
A2	1.850	2.150	0.073	0.085
b	1.110	1.360	0.044	0.054
b2	1.910	2.250	0.075	0.089
b4	2.910	3.250	0.115	0.128
c	0.510	0.750	0.020	0.030
D	20.800	21.300	0.819	0.839
E	15.500	16.100	0.610	0.634
E2	4.400	5.200	0.173	0.205
e	5.440 BSC		0.214 BSC	
L	19.720	20.220	0.776	0.796
L1	-	4.300	-	0.169
Q	5.600	6.000	0.220	0.236
P	3.400	3.800	0.134	0.150

### Order Information

Device	Package	Marking	Quantity	HSF Status
GSFA10200	TO-247	A2R710	50pcs / Tube	RoHS Compliant